

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Withdrawn) Atomic layer deposition arrangement comprising:
 - an evacuable chamber,
 - at least two atomic layer deposition sources within the chamber, wherein each atomic layer deposition source is isolated from the remainder of the chamber, and
 - means for conveying substrate through the evacuable chamber.
2. (Withdrawn) Atomic layer deposition arrangement according to claim 1 wherein the means for conveying substrate comprises a rotatable drum.
3. (Withdrawn) Atomic layer deposition arrangement according to claim 1 further comprising a grounded shield for each atomic layer deposition source.
4. (Withdrawn) Atomic layer deposition arrangement according to claim 1 further comprising a substrate source chamber adjacent to the evacuable chamber.
5. (Withdrawn) Atomic layer deposition arrangement according to claim 4 wherein the substrate source chamber comprises a first rotatable drum and a

second rotatable drum, the first rotatable drum having polymer film wrapped around the drum, wherein the polymer film is conveyed into the evacuable chamber, and the second rotatable drum receives the polymer film after the polymer film exits the evacuable chamber.

6. (Withdrawn) Atomic layer deposition arrangement according to claim 5 wherein the polymer film comprises at least one selected from the group consisting of polyethylene terephthalate, polyacrylate, polypropylene, low density polyethylene, high density polyethylene, ethylene vinyl alcohol, polyphenylpropyleneoxide, polyvinylchloride and polyamides.

7. (Withdrawn) Atomic layer deposition arrangement according to claim 6 wherein the polymer film comprises polyethylene terephthalate.

8. (Currently Amended) A method Method for preparing a coated substrate comprising:

providing an atomic layer deposition arrangement comprising an evacuable chamber, and at least two atomic layer deposition sources within the chamber, wherein each atomic layer deposition source is isolated from the remainder of the chamber,

conveying a substrate past each to the first of the at least one atomic layer deposition source in succession, and

exposing the substrate to each the at least one atomic layer deposition source as the substrate is conveyed past,
~~conveying the substrate to the next atomic layer deposition source, and~~
~~exposing the substrate to said next atomic layer deposition source.~~

9. (Currently amended) A method Method for preparing a coated substrate according to claim 8 wherein conveying as substrate past each atomic layer deposition source comprises carrying the substrate on a rotatable drum located in the chamber. comprising ~~conveying coated substrate out of the evacuable chamber conveying substrate by rolling a rotatable drum which carries the substrate.~~

10. (Canceled)

11. (Currently amended) A method Method for preparing a coated substrate according to claim 8 wherein the substrate is a polymer film.

12. (Currently amended) A method Method for preparing a coated substrate according to claim 11 wherein the polymer is comprises at least one selected from the group consisting of: polyethylene terephthalate, low density polyethylene, high density polyethylene, polypropylene, polycarbonate, polyvinylidene chloride, ethylene vinyl alcohol, polyacrylate, and polyamide or combinations thereof.

13. (Currently amended) A method Method for preparing a coated substrate
according to claim 8 wherein at least one ~~the first~~ atomic layer deposition source
is a source of trimethylaluminum.

14. (Currently amended) A method Method for preparing a coated substrate
according to claim 15 ~~13~~ wherein the oxidizing agent is ~~selected from the group~~
~~consisting of~~ oxygen, nitrous oxide, or ~~and~~ ozone.

15. (Currently amended) A method Method for preparing a coated substrate
according to claim 8 wherein at least one ~~the first~~ atomic layer deposition source
is a source of trimethylaluminum and ~~the next~~ atomic layer deposition source is a
source of oxidizing agent.

16. (Canceled)

17. (Currently amended) A method Method for forming a coated substrate
according to claim 8 ~~16~~ wherein conveying a substrate past each atomic layer
deposition source comprises further comprising
providing a first rotatable substrate source drum and a second rotatable
drum in the substrate source chamber, the first rotatable drum having substrate
polymer film wrapped there around the drum, and providing a rotatable collection
drum,

rotating the first rotatable substrate source drum and conveying the substrate polymer film into the evacuable chamber, and
rotating the collection second rotatable drum and receiving the substrate polymer film exiting the evacuable chamber.

18. (Currently amended) A method Method for forming a coated substrate according to claim 8 further comprising introducing an inert gas into the evacuable chamber.

19. (Currently amended) A method Method for forming a coated substrate according to claim 8 wherein the inert gas is selected from the group consisting of argon or and oxygen.

20. (Currently amended) A method Method for forming a coated substrate according to claim 8 wherein the substrate is a polymer film and wherein a barrier coating having which has a thickness of 400 Å to 50 Å is formed on the polymer film.